

Virtual Workshop on Advanced Packaging for Energy Efficient Microelectronics

Register Now!

Virtual Webinar

January 12-13, 2022, 12:30-3:30pm EST

Hosted by the U.S. Department of Energy Advanced Manufacturing Office

with the National Institute of Standards and Technology (NIST)

This webinar will be focused on emerging technologies and opportunities to overcome key barriers in advanced packaging **to improve energy efficiency** of 3D microelectronics.

This webinar will discuss the state-of-the art and trends, drivers, and challenges for three critical energy-related topics for advanced packaging of 3D microelectronics: thermal management, I/O and interconnects, and metrology.

Register online, here: https://yesevents.com/AMO_Semiconductors

Read the report on our first workshop on integrated sensor systems [here](#)